

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC042NE7NS3 G	**Issued**	11. November 2019
MA#	MA001507780		
Package	PG-TDSON-8-39	**Weight***	114.31 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	3.86	3.86	38613	38613
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.048	0.04		424	
	non noble metal	copper	7440-50-8	48.352	42.30	42.35	422985	423536
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	501	501
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		680	
	plastics	epoxy resin	-	6.145	5.38		53752	
	inorganic material	silicondioxide	60676-86-0	32.667	28.58	34.03	285771	340203
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13297	13297
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.070	0.06		609	
	noble metal	silver	7440-22-4	0.087	0.08		761	
	non noble metal	lead	7439-92-1	3.322	2.91	3.05	29057	30427
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1312	
	non noble metal	copper	7440-50-8	16.910	14.79	14.93	147930	149434
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2599	2603
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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